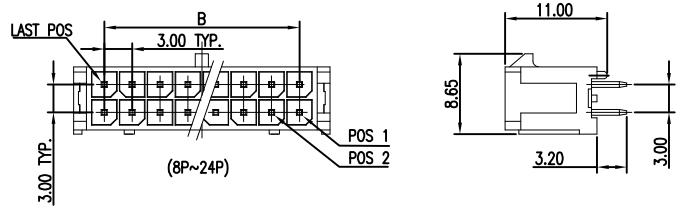
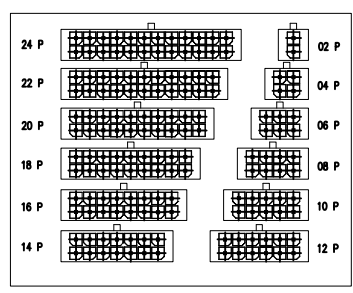
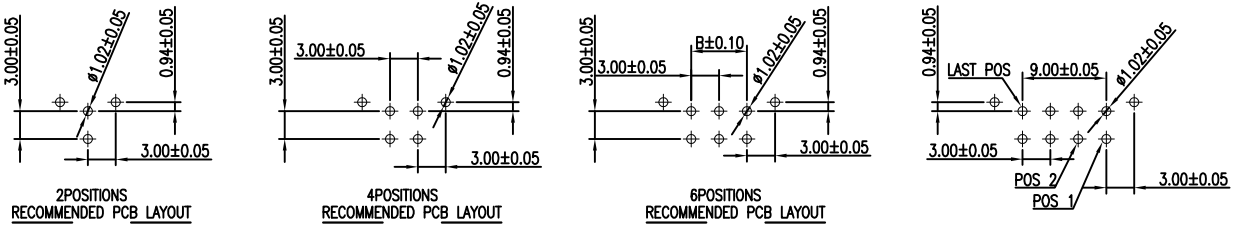
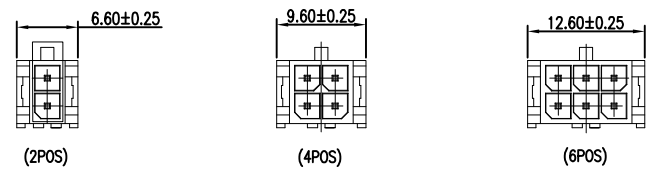


NOTE:
 1.MATERIAL:
 HOUSING:THERMOPLASTIC HIGH TEMPERATURE. COLOR-BLACK
 CONTACT: COPPER ALLOY.
 2.CONTACT FINISH:
 CONTACT:80u" MIN TIN ,PLATED OVER 50U" MIN NICKEL PLATED
 3.DIMENSIONAL :

P/N	POS	A	B
1-2834216-1	2	6.60	---
1-2834216-2	4	9.60	3.00
1-2834216-3	6	12.60	6.00
1-2834216-4	8	15.60	9.00
1-2834216-5	10	18.60	12.00
1-2834216-6	12	21.60	15.00
1-2834216-7	14	24.60	18.00
1-2834216-8	16	27.60	21.00
1-2834216-9	18	30.60	24.00
2-2834216-1	20	33.60	27.00
2-2834216-2	22	36.60	30.00
2-2834216-3	24	39.60	33.00



THIS DRAWING IS A CONTROLLED DOCUMENT. DWG NO: GEORGE FU 070dec2016
 SHI MING 070dec2016
 SHI MING 070dec2016
 NAME: 3.0MM PITCH WAFER (VERTICAL) DIP TYPE
 PROJECT SPEC: 108-137257
 APPLICATION SPEC: 114-137257
 VERNO: -
 SIZE: CAGE CODE DRAWING NO: A200779
 C-2834216
 RESTRICTED TO: -
 SCALE: 1:1 SHEET 1 OF 2 REV A



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 RESTRICTED TO: -
 SCALE: 1:1 SHEET 2 OF 2 REV A

单击下面可查看定价，库存，交付和生命周期等信息

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